TRADEMARK ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	SECURITY INTEREST

CONVEYING PARTY DATA

Name	Formerly	Execution Date	Entity Type
RJR POLYMERS, INC.		10/18/2012	CORPORATION: CALIFORNIA

RECEIVING PARTY DATA

Name:	SILICON VALLEY BANK
Street Address:	380 Interlocken Crescent, Suite 600
City:	Broomfield
State/Country:	COLORADO
Postal Code:	80021
Entity Type:	CORPORATION: CALIFORNIA

PROPERTY NUMBERS Total: 2

Property Type	Number	Word Mark
Registration Number:	4126090	R PAK
Registration Number:	2529221	THE TOTAL ELECTRONIC PACKAGE SOLUTION

CORRESPONDENCE DATA

Fax Number: 4049626571
Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.
Phone: 404.885.3335
Email: ben.wiles@troutmansanders.com
Correspondent Name: BENJAMIN C. WILES
Address Line 1: TROUTMAN SANDERS LLP
Address Line 2: 600 PEACHTREE STREET NE, SUITE 5200
Address Line 4: ATLANTA, GEORGIA 30308

ATTORNEY DOCKET NUMBER:	220763.001176
NAME OF SUBMITTER:	Benjamin C. Wiles
Signature:	/Benjamin C. Wiles 63174/

CH $65.00 4126090

Date:	11/05/2012

Total Attachments: 8
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INTELLECTUAL PROPERTY SECURITY AGREEMENT

THIS INTELLECTUAL PROPERTY SECURITY AGREEMENT is entered into as of October 18, 2012 by and between SILICON VALLEY BANK, a California corporation ("**Bank**") and RJR POLYMERS, INC., a California corporation ("**Grantor**").

RECITALS

A. Bank has agreed to make certain advances of money and to extend certain financial accommodation to Grantor (the "**Loans**") in the amounts and manner set forth in that certain Amended and Restated Loan and Security Agreement by and between Bank and Grantor dated as of the date hereof (as the same may be amended, modified, supplemented or restated from time to time, the "**Loan Agreement**"; capitalized terms used herein are used as defined in the Loan Agreement). Bank is willing to make the Loans to Grantor, but only upon the condition, among others, that Grantor shall grant to Bank a security interest in certain Copyrights, Trademarks, Patents, and Mask Works (as each term is described below) to secure the obligations of Grantor under the Loan Agreement.

B. Pursuant to the terms of the Loan Agreement, Grantor has granted to Bank a security interest in all of Grantor's right, title and interest, whether presently existing or hereafter acquired, in, to and under all of the Collateral.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, and intending to be legally bound, as collateral security for the prompt and complete payment when due of its obligations under the Loan Agreement, Grantor hereby represents, warrants, covenants and agrees as follows:

AGREEMENT

To secure its obligations under the Loan Agreement, Grantor grants and pledges to Bank a security interest in all of Grantor's right, title and interest in, to and under its intellectual property (all of which shall collectively be called the "**Intellectual Property Collateral**"), including, without limitation, the following:

(a) Any and all copyright rights, copyright applications, copyright registrations and like protections in each work or authorship and derivative work thereof, whether published or unpublished and whether or not the same also constitutes a trade secret, now or hereafter existing, created, acquired or held, including without limitation those set forth on Exhibit A attached hereto (collectively, the "**Copyrights**");

(b) Any and all trade secrets, and any and all intellectual property rights in computer software and computer software products now or hereafter existing, created, acquired or held;

(c) Any and all design rights that may be available to Grantor now or hereafter existing, created, acquired or held;

(d) All patents, patent applications and like protections including, without limitation, improvements, divisions, continuations, renewals, reissues, extensions and

continuations-in-part of the same, including without limitation the patents and patent applications set forth on Exhibit B attached hereto (collectively, the "**Patents**");

(e) Any trademark and servicemark rights, whether registered or not, applications to register and registrations of the same and like protections, and the entire goodwill of the business of Grantor connected with and symbolized by such trademarks, including without limitation those set forth on Exhibit C attached hereto (collectively, the "**Trademarks**");

(f) All mask works or similar rights available for the protection of semiconductor chips, now owned or hereafter acquired, including, without limitation those set forth on Exhibit D attached hereto (collectively, the "**Mask Works**");

(g) Any and all claims for damages by way of past, present and future infringements of any of the rights included above, with the right, but not the obligation, to sue for and collect such damages for said use or infringement of the intellectual property rights identified above;

(h) All licenses or other rights to use any of the Copyrights, Patents, Trademarks, or Mask Works and all license fees and royalties arising from such use to the extent permitted by such license or rights;

(i) All amendments, extensions, renewals and extensions of any of the Copyrights, Trademarks, Patents, or Mask Works; and

(j) All proceeds and products of the foregoing, including without limitation all payments under insurance or any indemnity or warranty payable in respect of any of the foregoing.

This security interest is granted in conjunction with the security interest granted to Bank under the Loan Agreement. The rights and remedies of Bank with respect to the security interest granted hereby are in addition to those set forth in the Loan Agreement and the other Loan Documents, and those which are now or hereafter available to Bank as a matter of law or equity. Each right, power and remedy of Bank provided for herein or in the Loan Agreement or any of the Loan Documents, or now or hereafter existing at law or in equity shall be cumulative and concurrent and shall be in addition to every right, power or remedy provided for herein and the exercise by Bank of any one or more of the rights, powers or remedies provided for in this Intellectual Property Security Agreement, the Loan Agreement or any of the other Loan Documents, or now or hereafter existing at law or in equity, shall not preclude the simultaneous or later exercise by any person, including Bank, of any or all other rights, powers or remedies.

[Signature Page Follows.]

TRADEMARK
REEL: 004893 FRAME: 0713

IN WITNESS WHEREOF, the parties have caused this Intellectual Property Security Agreement to be duly executed by its officers thereunto duly authorized as of the first date written above.

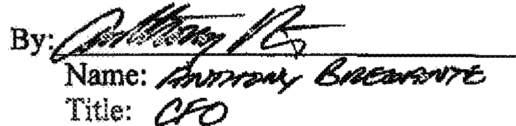
GRANTOR:

Address of Grantor:

RJR POLYMERS, INC.

7875 Edgewater Drive
Oakland, California 94621

Attn:



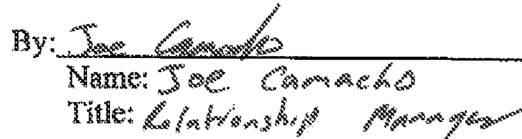
By:
Name:
Title: CFO

BANK:

Address of Bank:

SILICON VALLEY BANK

380 Interlocken Crescent, Suite 600
Broomfield, Colorado 80021



By:
Name: Joe Camacho
Title: Relationship Manager

Attn: Mike Kalicak

[Signature Page to Intellectual Property Security Agreement]

EXHIBIT A

Copyrights

Description	Registration/ Application Number	Registration/ Application Date
None		

EXHIBIT B

Patents

Description	Registration/ Application Number	Registration/ Application Date
MODULAR LOW STRESS PACKAGE TECHNOLOGY	8,153,474 12/903,761	April 10, 2012
USE OF DIVERSE MATERIALS IN AIR-CAVITY PACKAGING OF ELECTRONIC DEVICES	6,511,866 09/904,583	January 28, 2003
LEAD FRAME MOISTURE BARRIER FOR MOLDED PLASTIC ELECTRONIC PACKAGES	6,214,152 09/273,608	April 10, 2001
INVERTED STAMPING PROCESS	5,816,158 08/952,336	October 6, 1998
METHOD OF ASSEMBLING INTEGRATED CIRCUIT PACKAGE	5,706,579 08/631,649	January 13, 1998
INTEGRATED CIRCUIT PACKAGES WITH HEAT DISSIPATION FOR HIGH CURRENT LOAD	5,572,070 08/383,511	November 5, 1996
ISO-THERMAL SEAL PROCESS FOR ELECTRONIC DEVICES	5,056,296 07/502,558	October 15, 1991
MODULAR LOW STRESS PACKAGE TECHNOLOGY	12/903,779	October 13, 2010
MODULAR LOW STRESS PACKAGE TECHNOLOGY	12/903,772	October 13, 2010
MODULAR LOW STRESS PACKAGE TECHNOLOGY	12/903,752	October 13, 2010
MODULAR LOW STRESS PACKAGE TECHNOLOGY	12/903,734	October 13, 2010
USE OF DIVERSE MATERIALS IN AIR-CAVITY PACKAGING OF ELECTRONIC DEVICES	PCT/US2002/019501	June 19, 2002
LEAD FRAME MOISTURE BARRIER FOR MOLDED PLASTIC ELECTRONIC PACKAGES	PCT/US2000/007710	March 22, 2000
INVERTED STAMPING PROCESS	PCT/US1997/018173	October 7, 1997

ELECTRONIC PACKAGES CONTAINING MICROSPHERE SPACERS	PCT/US1997/013324	July 25, 1997

Active 20108154v1 220763.001176

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EXHIBIT C

Trademarks

Description	Registration/ Application Number	Registration/ Application Date
R PAK	4,126,090	April 10, 2012
THE TOTAL ELECTRONIC PACKAGE SOLUTION	2,529,221	January 15, 2002

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EXHIBIT D

Mask Works

Description	Registration/ Application Number	Registration/ Application Date
None		

Active 20108154v1 220763.001176